

Appl. No. : 09/389,720  
Filed : September 3, 1999

## AMENDMENTS TO THE SPECIFICATION

### IN THE SPECIFICATION:

Please replace the paragraph beginning at page 6, line 15, with the following rewritten paragraph:

In one embodiment, the substrate film 18 (Figure 3) is fabricated from polymidepolyimide. Such substrate films 18 are commercially available from a wide variety of sources, for example, 3M, Casio, Shinko, Rite Flex and others. Typically, the fabrication of the film or tape 18 begins with providing a polymidepolyimide tape which is sandwiched on either side by a layer of copper and an outer layer of solder resist/mask. The desired electrical "artwork" is then etched on the polymidepolyimide tape. The skilled artisan will understand, however, that a variety of other non-conductive materials and processes can be used to create the substrate film 18.

Please replace the paragraph beginning at page 12, line 7, with the following rewritten paragraph:

In another embodiment, as shown in Figure 6, the substrate film carrier 20 is formed with the substrate film 18 to create the carrier-film assembly 21. In one embodiment, the carrier 20 and the film 18 are fabricated from polymidepolyimide. The skilled artisan will understand, however, that a variety of materials can be used for the carrier 20 and the film 18. Referring to Figure 6, the carrier 20 and the film 18 may be manufactured by using known techniques, such as molding.

Please replace the paragraph beginning at page 13, line 4, with the following rewritten paragraph:

In another embodiment, as shown in Figure 7, the substrate film carrier 20 comprises a plurality of layers 74 of material. In one embodiment, the layers 74 are polymidepolyimide. In other embodiments, one or more of the layers 74 are metallic, for example, copper, and/or solder mask. These latter embodiments may be desirable especially in the situation, as indicated above, in which fabrication of the electrical "artwork" on the substrate film 18 utilizes layers of copper and solder resist.

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Please replace the paragraph beginning at page 13, line 10, with the following rewritten paragraph:

For example, one or more layers 74 can be polymidepolyimide, one or more layers 74 can be copper, and one or more layers 74 can be solder mask. The thickness of each layer 74 can be controlled, as required or desired. Those skilled in the art will recognize that a number of materials may be used to fabricate the layered carrier 20 shown in Figure 7.